

**IN THE CLAIMS:**

1-52. (cancelled)

53. (currently amended) An electronic component to have an electrical component incorporated thereon, the electronic component comprising:

- a substrate having
  - at least a front substrate layer with a front surface for receiving the electrical component and
  - conductive vias provided through the substrate or at least a front layer thereof for electrical connection to the electrical component;

characterised in that the electronic component further comprises:

- grooves provided in the front surface of the substrate with separate conductive lines, where each conductive line is formed entirely within one of ~~being formed completely within~~ the grooves, the conductive lines for electrical connection to the electrical component.

54. (original) An electronic component according to claim 53, wherein the front substrate layer is of ceramic and the grooves are formed by serration of a tape-casting, doctor blade.

55. (original) An electronic component according to claim 53, wherein the front substrate layer is of ceramic and the grooves are formed by laser cutting.

56. (original) An electronic component according to claim 53, wherein the front substrate layer is of ceramic and the grooves are formed by chemical etching

57. (previously presented) An electronic component according to claim 53, wherein the conductive lines are of metal deposited by sputtering.

58. (previously presented) An electronic component according to claim 53, wherein the conductive lines are of metal deposited by vacuum deposition.

59. (previously presented) An electronic component according to claim 53, wherein the conductive lines are a fired slurry deposition.

60-86. (cancelled)